

# SOT1025-1

plastic thermal enhanced ultra thin quad flat package; no leads; 60 terminals; UTLP based, 0.5 mm pitch, 4 mm x 6 mm x 0.55 mm body

13 August 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HUQFN60U
<b>Package type industry code</b>	HUQFN60U
<b>Package style descriptive code</b>	HUQFN (thermal enhanced ultra thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-11-2007
<b>Manufacturer package code</b>	SOT1025-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	5.9	6	6.1	mm
seated height	-	-	0.6	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	60	-	

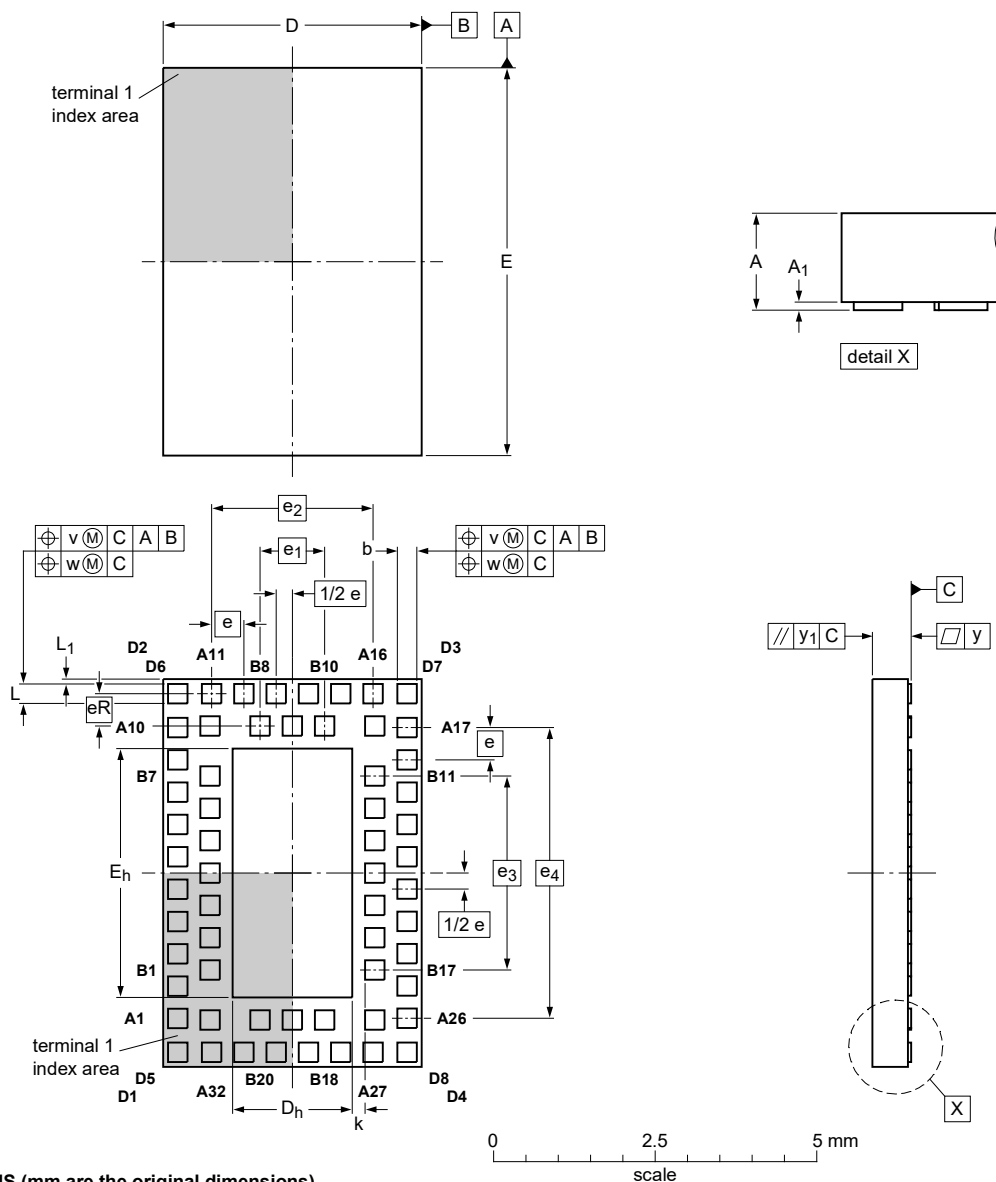


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## 2 Package outline

HUQFN60U: plastic thermal enhanced ultra thin quad flat package; no leads  
60 terminals; UTLP based; body 4 x 6 mm

SOT1025-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max	A <sub>1</sub>	b	D	D <sub>h</sub>	E	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	e <sub>3</sub>	e <sub>4</sub>	eR	k	L	L <sub>1</sub>	v	w	y	y <sub>1</sub>
mm	0.6	0.05 0.00	0.35 0.25	4.1 3.9	1.9 1.8	6.1 5.9	3.9 3.8	0.5	1	2.5	3	4.5	0.5	0.25 0.15	0.35 0.25	0.125 0.025	0.07	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1025-1	---	---	---			07-08-28 07-11-14

Figure 1. Package outline HUQFN60U (SOT1025-1)

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### 3 Legal information

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Contents

1	Package summary .....	1
2	Package outline .....	2
3	Legal information .....	3